

FINEPLACER® Pico

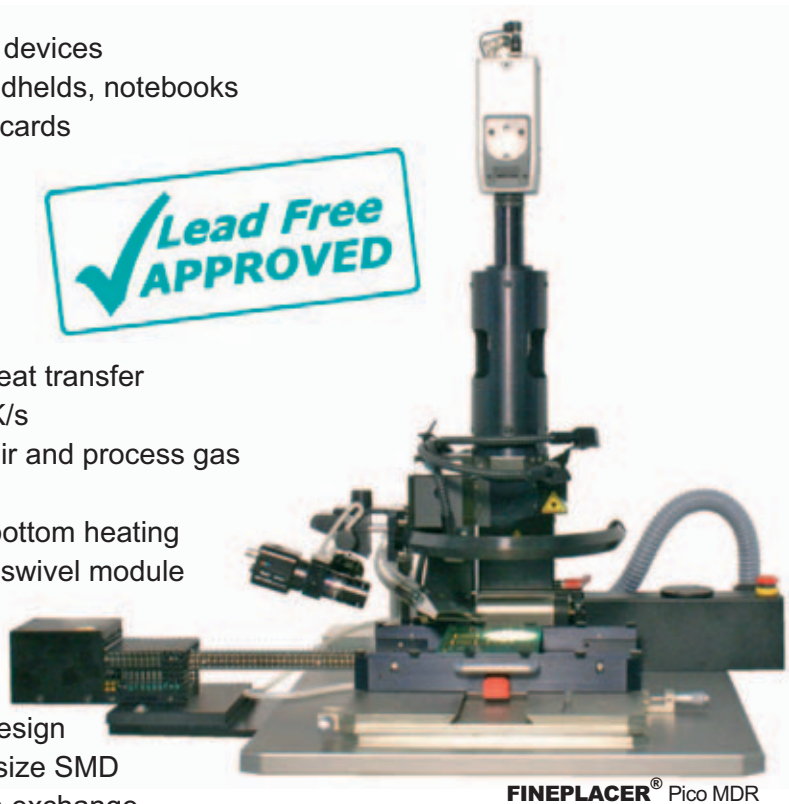
Mobile Device Rework

Fields of Application

- Whole range of rework applications
- Especially suitable for rework of mobile devices
 - Cellular phones, PDAs, gaming handhelds, notebooks
 - Bluetooth, WLAN devices, memory cards
 - Portable medical equipment

Benefits

- Better than 5 µm placement accuracy
- COMISS IV - reflow module
 - Repeatable profiling by controlled heat transfer
 - Fast temperature ramping max. 70K/s
 - Programmable switching between air and process gas
 - Real time process monitoring
 - Multi section capability for top and bottom heating
- User independent rework by motorized swivel module
 - Programmable working distance (z)
 - Defined force by automatic control
 - Repeatable rework results
- Maximum of flexibility due to modular design
- Sufficient back up power also for large size SMD
- World wide profiling - solder profile data exchange
- Highest grade of reproducibility



FINEPLACER® Pico MDR

Complete Rework Technologies

- Desoldering of components
- Residual solder removal
- Paste printing
- Placement and reflow of new components



RF-shields



In situ process observation

Features

Placement accuracy	< 5 µm
Max. board size	234 mm x 410 mm
Top / bottom heater	380°C / 360°C
Gas flow top / bottom	70l/min / 80l/min
Temperature ramping	70K/s
Field of application	Advanced rework



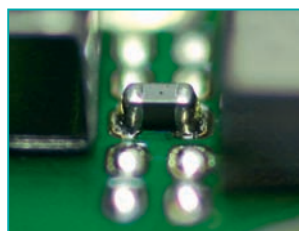
High density board



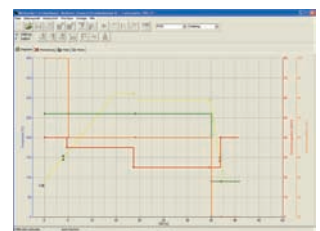
Motorized swivel module

System Configuration

Motorized swivel module
COMISS IV reflow module
Solder removal module
Video optic
Localized air bottom heater
Vario PLUS observing and inspection video module



Restricted accessibility



Graphical user interface

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Small Passives Rework

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Advanced Rework

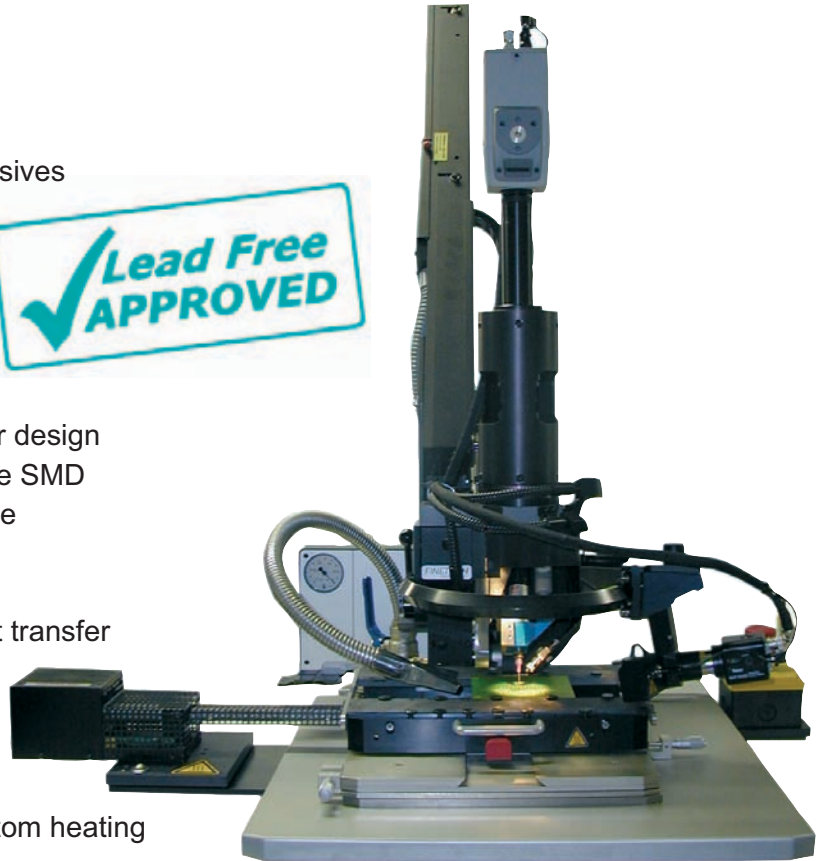
Micro Assembly

Fields of Application

- Whole range of rework applications
- Especially suitable for rework of small passives (0402, 0201, 01005)

Benefits

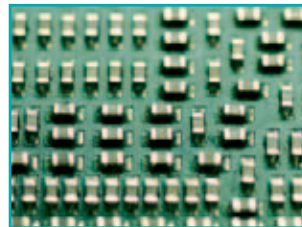
- Better than 5 µm placement accuracy
- Integrated solder dispense capability
- Maximum level of flexibility due to modular design
- Sufficient back up power also for large size SMD
- World wide profiling - profile data exchange
- Highest grade of reproducibility
- COMISS IV - reflow module
 - Repeatable profiling by controlled heat transfer
 - Fast temperature ramping max. 70K/s
 - Programmable switching between air and process gas
 - Real time process monitoring
 - Multi section capability for top and bottom heating



FINEPLACER® Pico SPR

Complete Rework Technologies

- Desoldering of components
- Residual solder removal
- Solder paste dispensing or paste printing
- Placement and reflow of new components



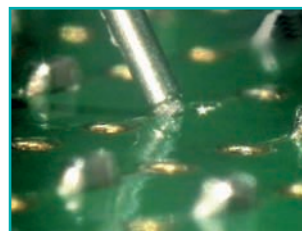
Field of 0201 components



Dispenser module

Features

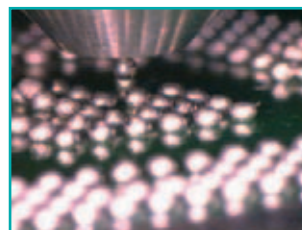
Placement accuracy	< 5 µm
Max. board size	234 mm x 410 mm
Top / bottom heater	380°C / 360°C
Gas flow top / bottom	70l/min / 80l/min
Temperature ramping	70K/s
Field of application	Advanced Rework



Solder dispensing

System Configuration

Dispenser module
COMISS IV reflow module
Solder removal module
Video Optic
Localized air bottom heater
Vario PLUS observing and inspection video module



Single ball reballing



Dispense detail

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